Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	0	("20040212030.pn.").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/19 18:08
L2	2	"20040212030".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/19 18:09
L3	2	2 and "1134"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/19 18:10
L4	2	2 and ("1134" solder resist)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/19 18:32
L5	1	2 and ("1134" and (solder near2 resist) same polyphenylene)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/19 18:29
L6	194133	photodefin\$8 novolak polynororene polyimide polyybenzoxazole	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/19 20:13
L7	2	2 and ("1134" (solder adj resist) same 6)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/19 18:36
L8	2	2 and ("1134" (solder adj resist) and (photodefin\$8 photoresist))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/19 18:37
L9	0	2 and ((photodefin\$8 photoresist))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/19 18:46

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L10	2	2 and (via copper cu)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/19 18:49
L11	1	2 and (via same (copper cu))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/19 19:04
L12	2	"20040245616".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/19 19:04
L13	1	12 and 6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/19 19:05
L14	1	12 and 6 and (nonphotodefin\$8 non-photodefin\$8)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/19 19:06
L15	23525	(multichip multi-chip multi adj chip) adj module mcm	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/19 19:43
L16	193685	novolak polynororene polyimide polyybenzoxazole	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/19 19:44
L17	4125	15 and 16	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/19 19:45
L18	634247	via adj hole via-hole viahole plug	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/19 19:45
L19	1023	17 and 18	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/19 19:45

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L20	849	19 and (@ad < "20030606")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/19 20:15
L21	4930911	(resin\$4 epoxy photodefin\$4 light uv ultraviolet)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/19 20:12
L22	193685	novolak polynororene polyimide polyybenzoxazole	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/19 20:13
L23	99993	22 with 21	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/19 20:14
L24	446	23 and 18 and 15 and (@ad < "20030606")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/19 20:20
L25	381	asai-motoo.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/19 20:19
L26	364	25 and (@ad < "20030606")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/19 20:26
L27	85098	(bottom or under underneath lower backside back) near2 (ic die chip dice)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/19 20:27
L28	97782	(second! top upper third topside) near2 (ic die chip dice)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/19 20:28
L29	13	26 and (27 28)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/19 22:18

L30	3	"6908784".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/19 22:18
L31	1	30 and (resist photoresist pr light laser uv expos\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/19 22:52
L32	2	30 and (copper cu via)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/19 23:04
L33	1	30 and (photoimag\$6)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/19 23:04
L34	4656	((438/622) or (438/626) or (438/633) or (438/691)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/19 23:07